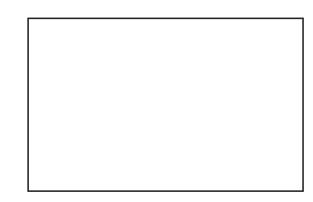


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REU	: Not In VersionControl		
	TID #: .TID					
PLOT NAME = Top Assembly Drawing	GENERATED : 8/21/2	2017 14:01:20		TEXAS INSTRUMENTS		



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30296	REV: A	SUN REV	: Not In VersionControl	
	TID #: .TID				
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/21/2	017 14:01:22		TEXAS INSTRUMENTS	

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